

# FCA16N60N

## N-Channel SupreMOS® MOSFET

600 V, 16 A, 199 mΩ

### Features

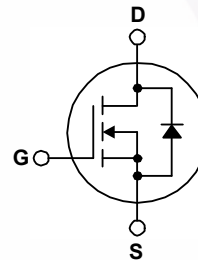
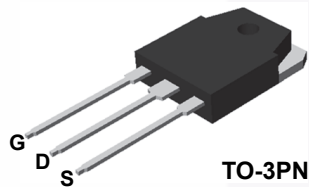
- $R_{DS(on)} = 170 \text{ m}\Omega$  (Typ.) @  $V_{GS} = 10\text{V}$ ,  $I_D = 8 \text{ A}$
- Ultra Low Gate Charge (Typ.  $Q_g = 40.2 \text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 176 \text{ pF}$ )
- 100% Avalanche Tested
- RoHS Compliant

### Application

- PDP TV
- AC-DC Power Supply

### Description

The SupreMOS® MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest  $R_{sp}$  on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.



### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	FCA16N60N	Unit
$V_{DSS}$	Drain to Source Voltage	600	V
$V_{GSS}$	Gate to Source Voltage	$\pm 30$	V
$I_D$	Drain Current	- Continuous ( $T_C = 25^\circ\text{C}$ )	16.0
		- Continuous ( $T_C = 100^\circ\text{C}$ )	10.1
$I_{DM}$	Drain Current	- Pulsed (Note 1)	48.0
$E_{AS}$	Single Pulsed Avalanche Energy	(Note 2)	355
$I_{AR}$	Avalanche Current	(Note 1)	5.3
$E_{AR}$	Repetitive Avalanche Energy	(Note 1)	1.34
dv/dt	MOSFET dv/dt		100
	Peak Diode Recovery dv/dt	(Note 3)	20
$P_D$	Power Dissipation	( $T_C = 25^\circ\text{C}$ )	134.4
		- Derate Above $25^\circ\text{C}$	1.08
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to +150	$^\circ\text{C}$
$T_L$	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds	300	$^\circ\text{C}$

### Thermal Characteristics

Symbol	Parameter	FCA16N60N	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.93	$^\circ\text{C}/\text{W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

## Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCA16N60N	FCA16N60N	TO-3PN	Tube	N/A	N/A	30 units

## Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 1\text{ mA}, V_{GS} = 0\text{ V}, T_C = 25^\circ\text{C}$	600	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{ mA}$ , Referenced to $25^\circ\text{C}$	-	0.73	-	$V/^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}$	-	-	10	$\mu\text{A}$
		$V_{DS} = 480\text{ V}, V_{GS} = 0\text{ V}, T_C = 125^\circ\text{C}$	-	-	100	
$I_{GSS}$	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{ V}, V_{DS} = 0\text{ V}$	-	-	$\pm 100$	nA

### On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\ \mu\text{A}$	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}, I_D = 8\text{ A}$	-	0.170	0.199	$\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 40\text{ V}, I_D = 8\text{ A}$	-	20	-	S

### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 100\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	1630	2170	pF
$C_{oss}$	Output Capacitance		-	70	95	pF
$C_{rss}$	Reverse Transfer Capacitance		-	5	10	pF
$C_{oss}$	Output Capacitance	$V_{DS} = 380\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	-	40	60	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V to } 480\text{ V}, V_{GS} = 0\text{ V}$	-	176	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 380\text{ V}, I_D = 8\text{ A}, V_{GS} = 10\text{ V}$ (Note 4)	-	40.2	52.3	nC
$Q_{gs}$	Gate to Source Gate Charge		-	6.7	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	12.9	-	nC
ESR	Equivalent Series Resistance (G-S)	$f = 1\text{ MHz}$	-	2.9	-	$\Omega$

### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 380\text{ V}, I_D = 8\text{ A}, V_{GS} = 10\text{ V}, R_G = 4.7\ \Omega$ (Note 4)	-	15.8	41.6	ns
$t_r$	Turn-On Rise Time		-	15.5	41.0	ns
$t_{d(off)}$	Turn-Off Delay Time		-	60.3	130.6	ns
$t_f$	Turn-Off Fall Time		-	20.2	50.4	ns

### Drain-Source Diode Characteristics

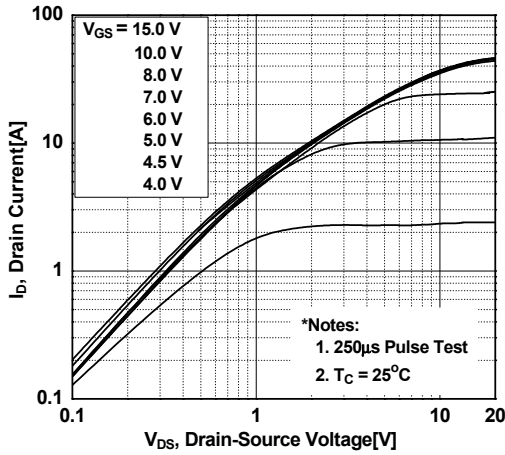
$I_S$	Maximum Continuous Drain to Source Diode Forward Current	-	-	16	A	
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current	-	-	48	A	
$V_{SD}$	Drain to Source Diode Forward Voltage	$V_{GS} = 0\text{ V}, I_{SD} = 8\text{ A}$	-	-	1.2	V
$t_{rr}$	Reverse Recovery Time	$V_{GS} = 0\text{ V}, I_{SD} = 8\text{ A}, di_F/dt = 100\text{ A}/\mu\text{s}$	-	319	-	ns
$Q_{rr}$	Reverse Recovery Charge		-	4.4	-	$\mu\text{C}$

#### Notes:

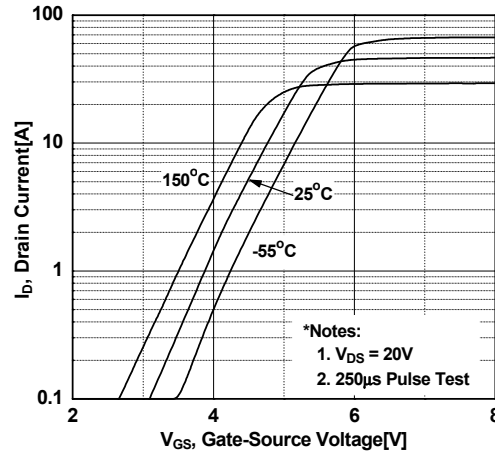
1. Repetitive rating; pulse-width limited by maximum junction temperature.
2.  $I_{AS} = 5.3\text{ A}, R_G = 25\ \Omega$ , starting  $T_J = 25^\circ\text{C}$ .
3.  $I_{SD} \leq 16\text{ A}, di/dt \leq 200\text{ A}/\mu\text{s}, V_{DD} = 380\text{ V}$ , starting  $T_J = 25^\circ\text{C}$ .
4. Essentially independent of operating temperature typical characteristics.

## Typical Performance Characteristics

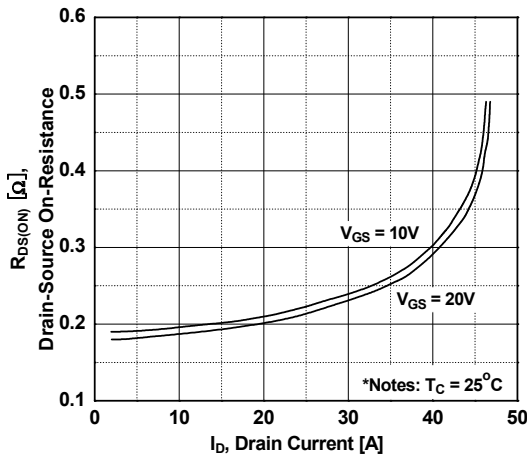
**Figure 1. On-Region Characteristics**



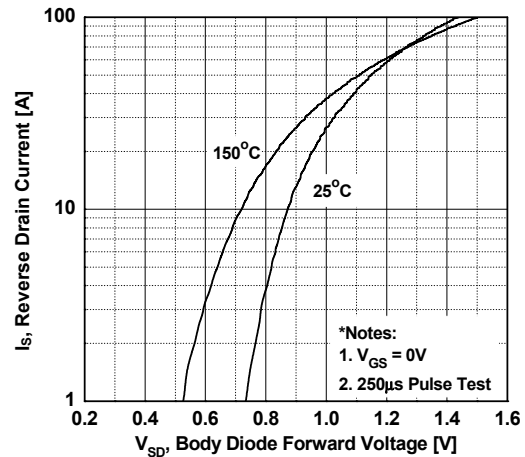
**Figure 2. Transfer Characteristics**



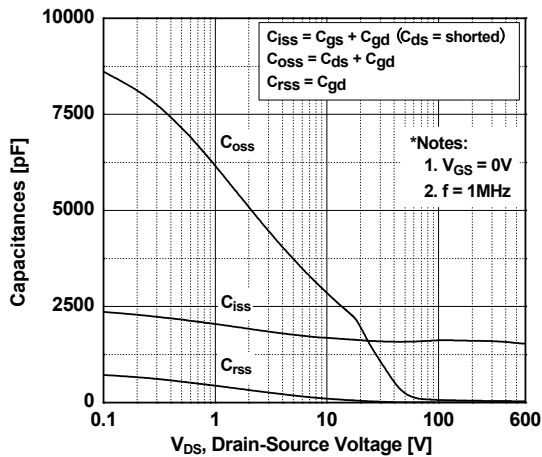
**Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage**



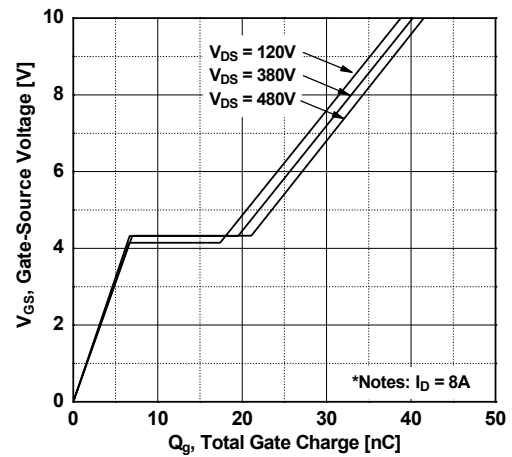
**Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature**



**Figure 5. Capacitance Characteristics**

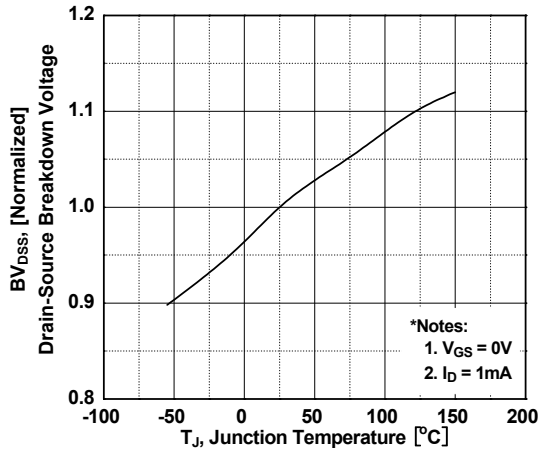


**Figure 6. Gate Charge Characteristics**

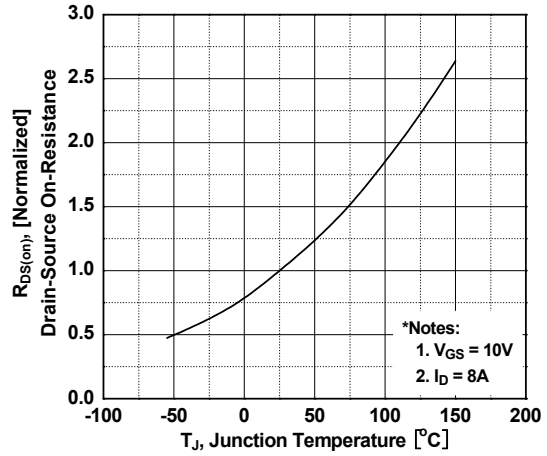


**Typical Performance Characteristics** (Continued)

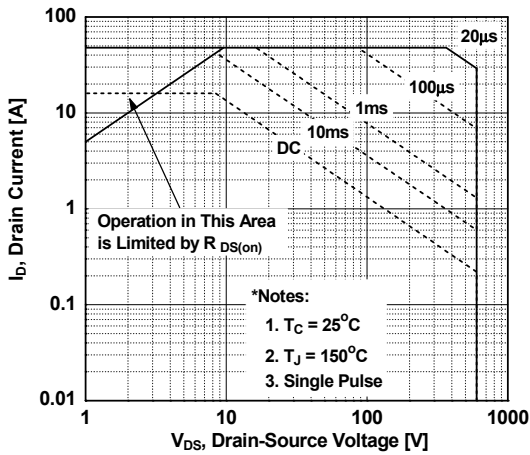
**Figure 7. Breakdown Voltage Variation vs. Temperature**



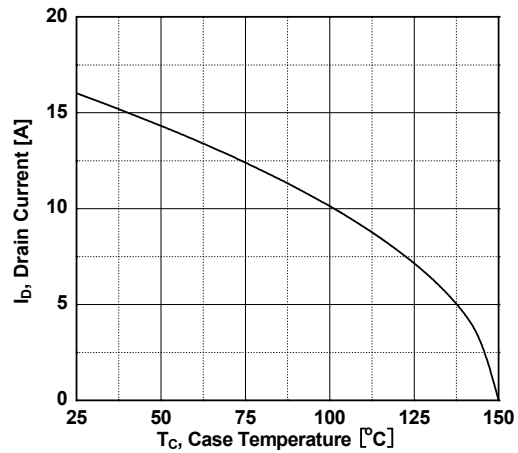
**Figure 8. On-Resistance Variation vs. Temperature**



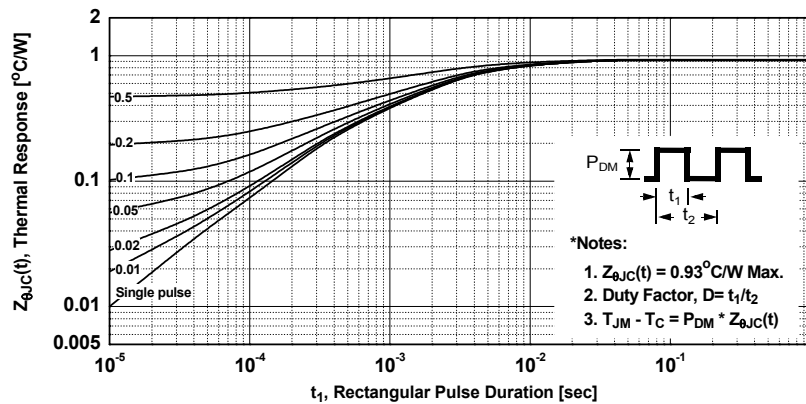
**Figure 9. Maximum Safe Operating Area**



**Figure 10. Maximum Drain Current vs. Case Temperature**



**Figure 11. Transient Thermal Response Curve**



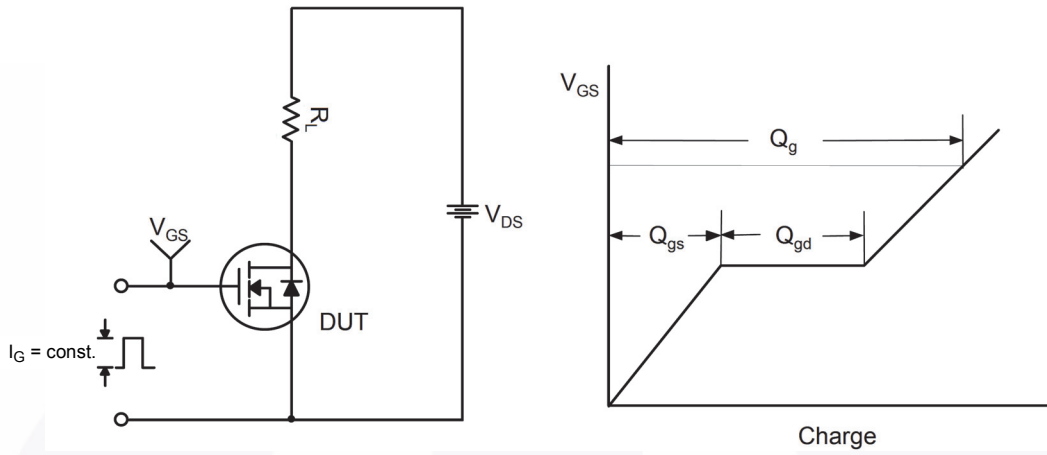


Figure 12. Gate Charge Test Circuit & Waveform



Figure 13. Resistive Switching Test Circuit & Waveforms



Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms

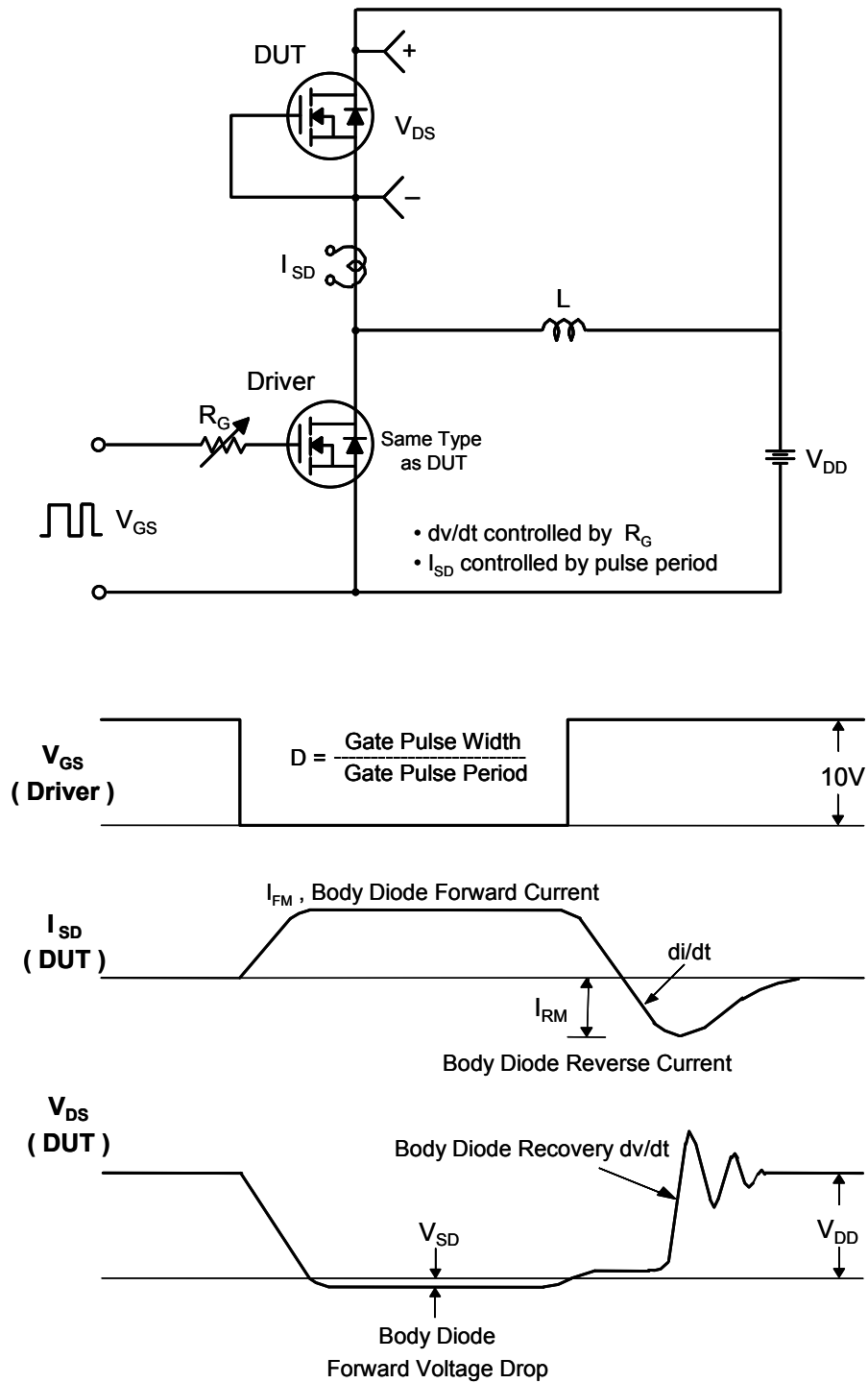
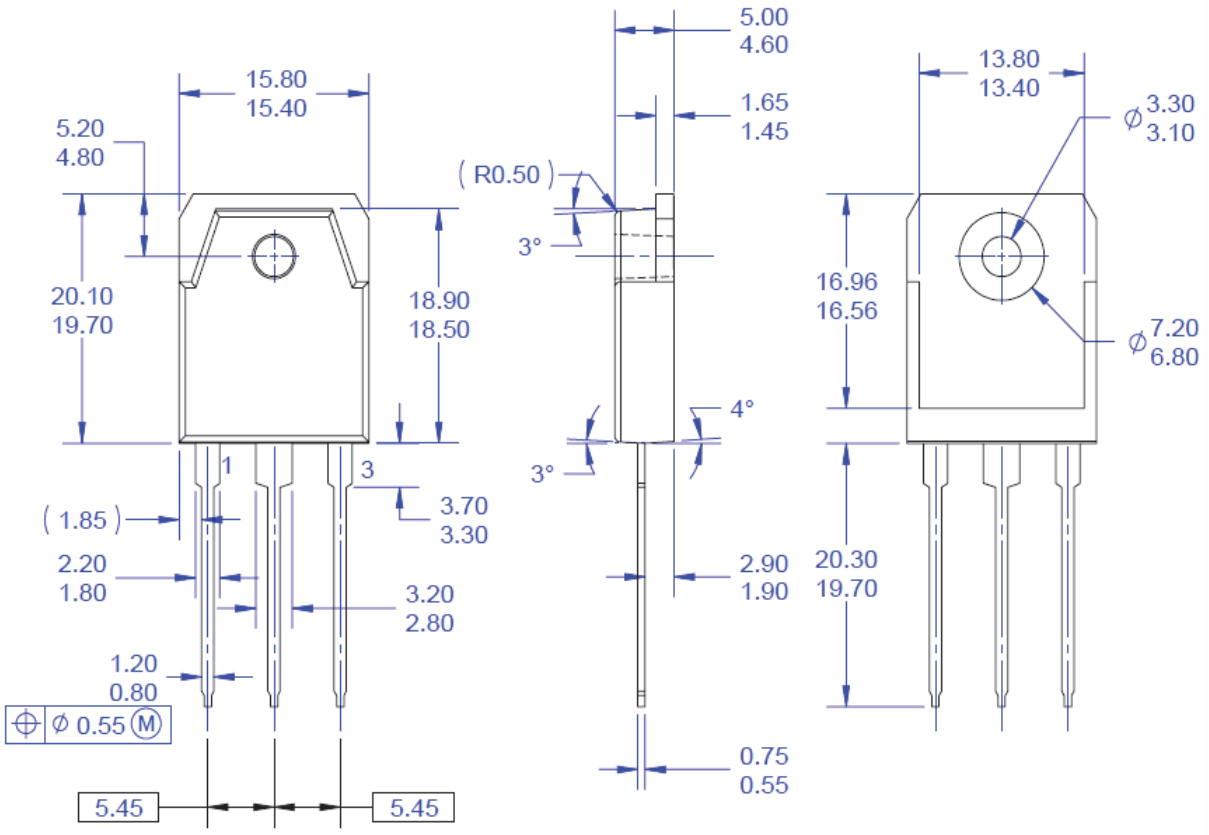


Figure 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms

**Mechanical Dimensions**



- NOTES: UNLESS OTHERWISE SPECIFIED
- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
  - B) ALL DIMENSIONS ARE IN MILLIMETERS.
  - C) DIMENSION AND TOLERANCING PER ASME14.5
  - D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
  - E) THIS PACKAGE IS INTENDED ONLY FOR T03PN.
  - F) DRAWING FILE NAME: T03P03AREV4.

**Figure 16. TO3, 3-Lead, Plastic, EIAJ SC-65**

Package drawings are provided as a service to customers considering Fairchild components. Drawings may change in any manner without notice. Please note the revision and/or date on the drawing and contact a Fairchild Semiconductor representative to verify or obtain the most recent revision. Package specifications do not expand the terms of Fairchild's worldwide terms and conditions, specifically the warranty therein, which covers Fairchild products.

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[http://www.fairchildsemi.com/package/packageDetails.html?id=PN\\_TT3P0-003](http://www.fairchildsemi.com/package/packageDetails.html?id=PN_TT3P0-003)

